



OPA342 OPA2342 OPA4342

www.ti.com

# Low-Cost, Low-Power, Rail-to-Rail OPERATIONAL AMPLIFIERS *MicroAmplifier*™ Series

# **FEATURES**

- LOW QUIESCENT CURRENT: 150µA typ
- RAIL-TO-RAIL INPUT
- RAIL-TO-RAIL OUTPUT (within 1mV)
- SINGLE SUPPLY CAPABILITY
- LOW COST
- MicroSIZE PACKAGE OPTIONS: SOT23-5

MSOP-8 TSSOP-14

BANDWIDTH: 1MHz
 SLEW RATE: 1V/μs
 THD + NOISE: 0.006%

## **APPLICATIONS**

- **COMMUNICATIONS**
- PCMCIA CARDS
- DATA ACQUISITION
- PROCESS CONTROL
- AUDIO PROCESSING
- ACTIVE FILTERS
- TEST EQUIPMENT
- CONSUMER ELECTRONICS

#### DESCRIPTION

The OPA342 series rail-to-rail CMOS operational amplifiers are designed for low-cost, low-power, miniature applications. They are optimized to operate on a single supply as low as 2.5V with an input common-mode voltage range that extends 300mV beyond the supplies.

Rail-to-rail input/output and high-speed operation make them ideal for driving sampling Analog-to-Digital Converters (ADC). They are also well suited for general-purpose and audio applications and providing I/V conversion at the output of Digital-to-Analog Converters (DAC). Single, dual, and quad versions have identical specs for design flexibility.

The OPA342 series offers excellent dynamic response with a quiescent current of only 250µA max. Dual and quad designs feature completely independent circuitry for lowest crosstalk and freedom from interaction.

PACKAGE	SINGLE OPA342	DUAL OPA2342	QUAD OPA4342
SOT23-5	~		
MSOP-8		~	
SO-8	~	~	
TSSOP-14			~
SO-14			~
DIP-14			V

SPICE MODEL available at www.burr-brown.com.



# SPECIFICATIONS: $V_S = 2.7V$ to 5.5V

At  $T_A$  = +25°C,  $R_L$  = 10k $\Omega$  connected to  $V_S/2$  and  $V_{OUT}$  =  $V_S/2$ , unless otherwise noted. **Boldface** limits apply over the temperature range,  $T_A$  = -40°C to +85°C.

			OPA342NA, UA OPA2342EA, UA OPA4342EA, UA, PA					
PARAMETER	CONDITION	MIN	TYP	MAX	UNITS			
OFFSET VOLTAGE Input Offset Voltage Voltage  TA = -40°C to +85°C  vs Temperature dVos/d*			±1 ±1 ±3	±6 ± <b>6</b>	mV <b>mV</b> μV/°C			
vs Temperature $dV_{OS}/d^{\circ}$ vs Power Supply PSRF $T_A = -40^{\circ}C$ to +85°C Channel Separation, dc f = 1kHz			30 0.2 132	200 <b>250</b>	μV/V μ <b>V/V</b> μV/V dB			
INPUT BIAS CURRENT Input Bias Current Input Bias Current Input Offset Current		s	±0.2 ee Typical Cur ±0.2	±10 <b>ve</b> = ±10	pA <b>pA</b> pA			
NOISE Input Voltage Noise, f = 0.1Hz to 50kHz Input Voltage Noise Density, f = 1kHz e Current Noise Density, f = 1kHz i			8 30 0.5		μVrms nV/√Hz fA/√Hz			
INPUT VOLTAGE RANGE  Common-Mode Voltage Range $V_{CI}$ Common-Mode Rejection Ratio CMRF $T_{\Delta} = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		-0.3 76 <b>74</b>	88	(V+) + 0.3	V dB <b>dB</b>			
Common-Mode Rejection Ratio CMRF $T_A = -40^{\circ}C$ to $+85^{\circ}C$ Common-Mode Rejection Ratio CMRF	$V_{S} = +5.5V, -0.3V < V_{CM} < 5.8V$ $V_{S} = +5.5V, -0.3V < V_{CM} < 5.8V$ $V_{S} = +2.7V, -0.3V < V_{CM} < 3V$	66 <b>64</b> 62	78 74		dB <b>dB</b> dB			
T <sub>A</sub> = -40°C to +85°C  INPUT IMPEDANCE  Differential  Common-Mode	V <sub>S</sub> = +2.7V, -0.3V < V <sub>CM</sub> < 3V	60	10 <sup>13</sup>    3 10 <sup>13</sup>    6		<b>dB</b> Ω    pF Ω    pF			
OPEN-LOOP GAIN  Open-Loop Voltage Gain $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	$\begin{array}{c} R_L = 100k\Omega, \ 10mV < V_O < (V+) - 10mV \\ R_L = 100k\Omega, \ 10mV < V_O < (V+) - 10mV \\ R_L = 5k\Omega, \ 400mV < V_O < (V+) - 400mV \\ R_L = 5k\Omega, \ 400mV < V_O < (V+) - 400mV \end{array}$	104 <b>100</b> 96 <b>90</b>	124		dB dB dB			
FREQUENCY RESPONSE  Gain-Bandwidth Product GBW  Slew Rate SF  Settling Time, 0.1% 0.01%  Overload Recovery Time  Total Harmonic Distortion + Noise, f = 1kHz THD+N	V <sub>S</sub> = 5.5V, 2V Step V <sub>S</sub> = 5.5V, 2V Step V <sub>IN</sub> • G = V <sub>S</sub>		1 1 5 8 2.5 0.006		MHz V/μs μs μs μs			
OUTPUT Voltage Output Swing from Rail <sup>(2)</sup> $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	$\begin{split} R_L &= 100 k \Omega, \ A_{OL} \geq 96 dB \\ R_L &= 100 k \Omega, \ A_{OL} \geq 104 dB \\ \mathbf{R_L} &= \mathbf{100k} \Omega, \ \mathbf{A_{OL}} \geq \mathbf{100dB} \\ \mathbf{R_L} &= \mathbf{5k} \Omega, \ A_{OL} \geq 96 dB \\ \mathbf{R_L} &= \mathbf{5k} \Omega, \ \mathbf{A_{OL}} \geq \mathbf{90dB} \end{split}$		1 3 20	10 10 400 400	mV mV mV mV			
Short-Circuit Current I <sub>St</sub> Capacitive Load Drive C <sub>LOAI</sub> POWER SUPPLY		S	±15 See Typical Cur	ve	mA			
Specified Voltage Range V.  Operating Voltage Range  Quiescent Current (per amplifier) I  T <sub>A</sub> = -40°C to +85°C		2.7	2.5 to 5.5 150	5.5 250 <b>300</b>	V V μA μ <b>A</b>			
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance		-40 -55 -65		+85 +125 +150	ဝိ ဝိ ဝိ			
Thermal Resistance $\theta_{J}$ , SOT23-5 Surface Mount MSOP-8 Surface Mount SO-8 Surface Mount TSSOP-14 Surface Mount SO-14 Surface Mount DIP-14			200 150 150 100 100 100		°C/W °C/W °C/W °C/W °C/W			

NOTES: (1)  $V_{OUT} = 0.25V$  to 3.25V. (2) Output voltage swings are measured between the output and power-supply rails.



#### **ABSOLUTE MAXIMUM RATINGS(1)**

Supply Voltage, V+ to V	7.5V
Signal Input Terminals, Voltage <sup>(2)</sup>	
Current <sup>(2)</sup>	10mA
Output Short-Circuit(3)	Continuous
Operating Temperature	55°C to +125°C
Storage Temperature	65°C to +150°C
Junction Temperature	150°C
Lead Temperature (soldering, 10s)	300°C
ESD Tolerance (Human Body Model)	4000V

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only. Functional operation of the device at these conditions, or beyond the specified operating conditions, is not implied. (2) Input terminals are diode-clamped to the power supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less. (3) Short-circuit to ground, one amplifier per package.

# ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

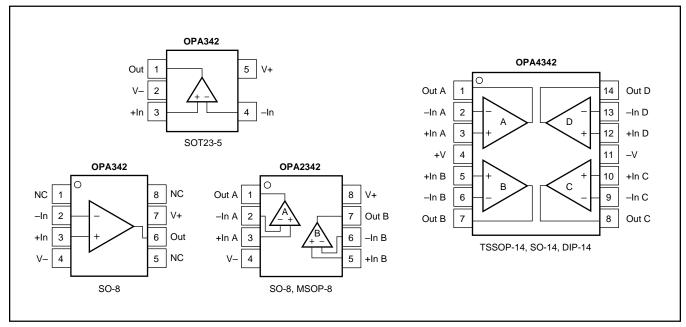
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### **PACKAGE/ORDERING INFORMATION**

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER <sup>(1)</sup>	TRANSPORT MEDIA
OPA342NA " OPA342UA	SOT23-5 " SO-8	331 " 182 "	-40°C to +85°C -40°C to +85°C	B42 " OPA342UA "	OPA342NA/250 OPA342NA/3K OPA342UA OPA342UA/2K5	Tape and Reel Tape and Reel Rails Tape and Reel
OPA2342EA OPA2342UA	MSOP-8 SO-8	337 " 182 "	-40°C to +85°C -40°C to +85°C	C42 " OPA2342UA "	OPA2342EA/250 OPA2342EA/2K5 OPA2342UA OPA2342UA/2K5	Tape and Reel Tape and Reel Rails Tape and Reel
OPA4342EA  OPA4342UA  OPA4342PA	TSSOP-14 "SO-14 "DIP-14	357 " 235 "	-40°C to +85°C -40°C to +85°C -40°C to +85°C	OPA4342EA " OPA4342UA " OPA4342PA	OPA4342EA/250 OPA4342EA/2K5 OPA4342UA OPA4342UA/2K5 OPA4342PA	Tape and Reel Tape and Reel Rails Tape and Reel Rails

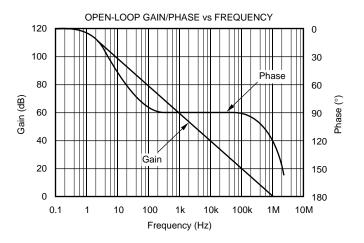
NOTE: (1) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /3K indicates 3000 devices per reel). Ordering 3000 pieces of "OPA342NA/3K" will get a single 3000-piece Tape and Reel.

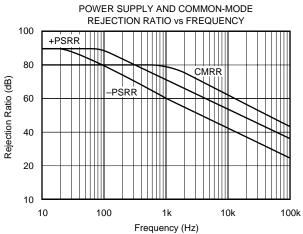
#### **PIN CONFIGURATIONS**

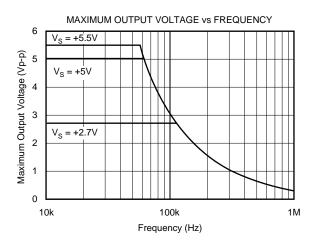


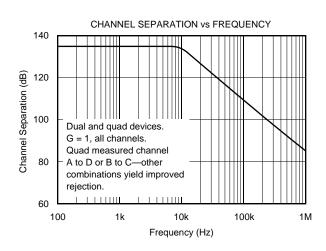


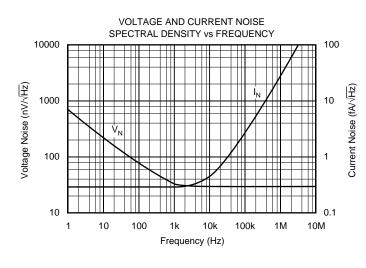
# TYPICAL PERFORMANCE CURVES

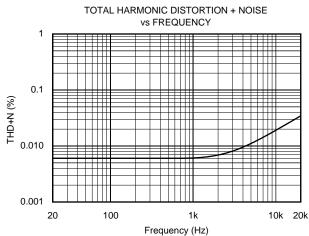






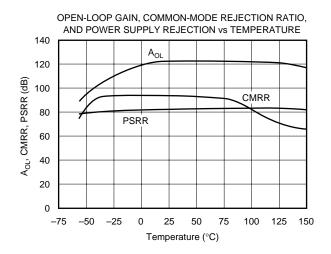


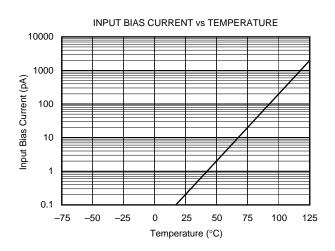


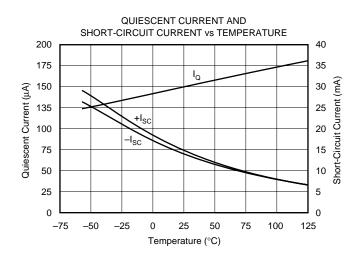


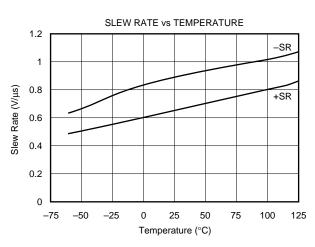


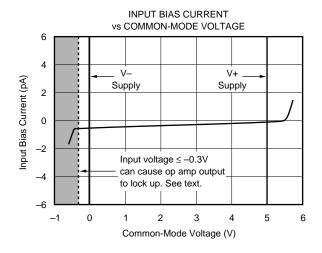
# TYPICAL PERFORMANCE CURVES (Cont.)

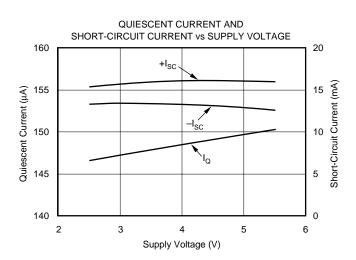






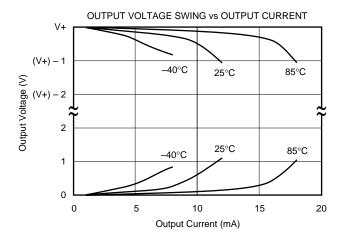


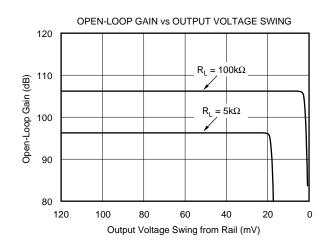


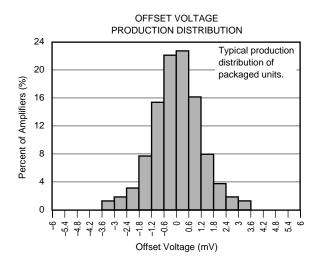


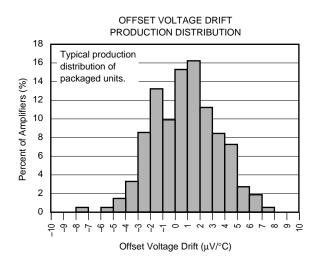


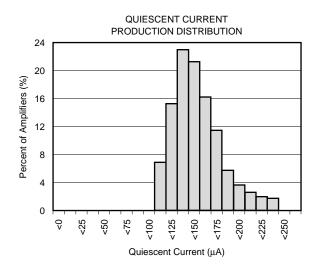
# **TYPICAL PERFORMANCE CURVES (Cont.)**

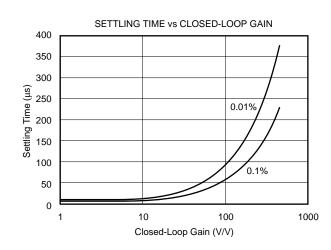






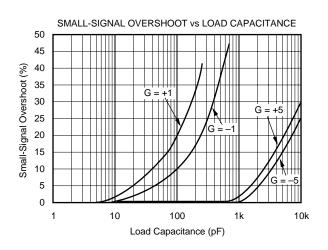


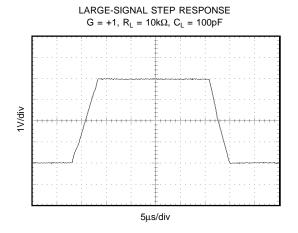


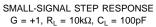


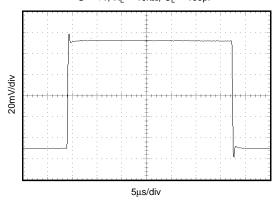


# **TYPICAL PERFORMANCE CURVES (Cont.)**











#### APPLICATIONS INFORMATION

OPA342 series op amps are unity gain stable and can operate on a single supply, making them highly versatile and easy to use.

Rail-to-rail input and output swing significantly increases dynamic range, especially in low supply applications. Figure 1 shows the input and output waveforms for the OPA342 in unity-gain configuration. Operation is from  $V_S=+5V$  with a  $10k\Omega$  load connected to  $V_S/2.$  The input is a 5Vp-p sinusoid. Output voltage is approximately 4.997Vp-p.

Power supply pins should be by passed with  $0.01 \mu F$  ceramic capacitors.

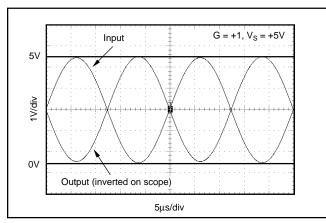


FIGURE 1. Rail-to-Rail Input and Output.

#### **OPERATING VOLTAGE**

OPA342 series op amps are fully specified and guaranteed from +2.7V to +5.5V. In addition, many specifications apply from -40°C to +85°C. Parameters that vary significantly with operating voltages or temperature are shown in the Typical Performance Curves.

#### **RAIL-TO-RAIL INPUT**

The input common-mode voltage range of the OPA342 series extends 300mV beyond the supply rails. This is achieved with a complementary input stage—an N-channel input differential pair in parallel with a P-channel differential pair (see Figure 2). The N-channel pair is active for input voltages close to the positive rail, typically (V+) - 1.3V to 300mV above the positive supply, while the P-channel pair is on for inputs from 300mV below the negative supply to approximately (V+) -1.3V. There is a small transition region, typically (V+) - 1.5V to (V+) - 1.1V, in which both pairs are on. This 400mV transition region can vary 300mV with process variation. Thus, the transition region (both stages on) can range from (V+) - 1.8V to (V+) - 1.4V on the low end, up to (V+) - 1.2V to (V+) - 0.8V on the high end. Within the 400mV transition region PSRR, CMRR, offset voltage, offset drift, and THD may be degraded compared to operation outside this region. For more information on designing with rail-to-rail input op amps, see Figure 3 "Design Optimization with Rail-to-Rail Input Op Amps."

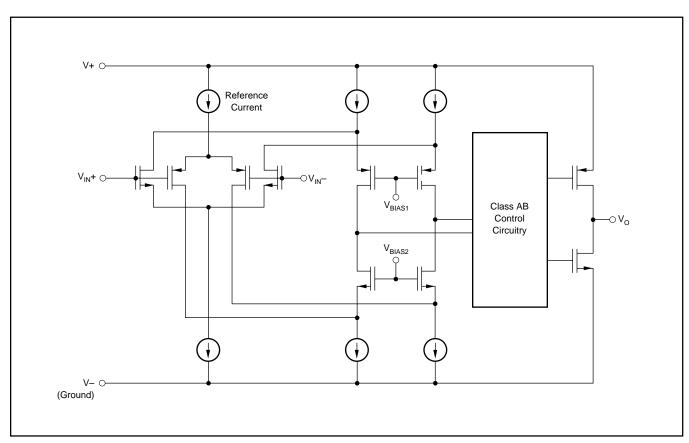


FIGURE 2. Simplified Schematic.



#### DESIGN OPTIMIZATION WITH RAIL-TO-RAIL INPUT OP AMPS

Rail-to-rail op amps can be used in virtually any op amp configuration. To achieve optimum performance, however, applications using these special double-input-stage op amps may benefit from consideration of their special behavior.

In many applications, operation remains within the common-mode range of only one differential input pair. However some applications exercise the amplifier through the transition region of both differential input stages. Although the two input stages are laser trimmed for excellent matching, a small discontinuity may occur in this transition. Careful selection of the circuit configuration, signal levels and biasing can often avoid this transition region.

With a unity-gain buffer, for example, signals will traverse this transition at approximately 1.3V below V+ supply and may exhibit a small discontinuity at this point.

The common-mode voltage of the non-inverting amplifier is equal to the input voltage. If the input signal always remains less than the transition voltage, no discontinuity will be created. The closed-loop gain of this configuration can still produce a rail-to-rail output.

Inverting amplifiers have a constant common-mode voltage equal to  $V_B$ . If this bias voltage is constant, no discontinuity will be created. The bias voltage can generally be chosen to avoid the transition region.

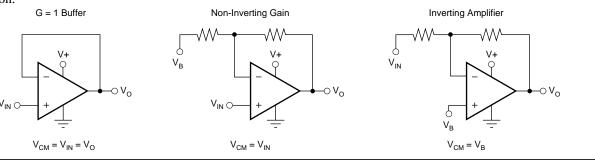


FIGURE 3. Design Optimization with Rail-to-Rail Input Op Amps.

#### **COMMON-MODE REJECTION**

The CMRR for the OPA342 is specified in several ways so the best match for a given application may be used. First, the CMRR of the device in the common-mode range below the transition region ( $V_{CM} < (V+) - 1.8V$ ) is given. This specification is the best indicator of the capability of the device when the application requires use of one of the differential input pairs. Second, the CMRR at  $V_S = 5.5V$  over the entire common-mode range is specified. Third, the CMRR at  $V_S = 2.7V$  over the entire common-mode range is provided. These last two values include the variations seen through the transition region.

#### INPUT VOLTAGE BEYOND THE RAILS

If the input voltage can go more than 0.3V below the negative power supply rail (single-supply ground), special precautions are required. If the input voltage goes sufficiently negative, the op amp output may lock up in an inoperative state. A Schottky diode clamp circuit will prevent this—see Figure 4. The series resistor prevents excessive current (greater than 10mA) in the Schottky diode and in the internal ESD protection diode, if the input voltage can exceed the positive supply voltage. If the signal source is limited to less than 10mA, the input resistor is not required.

#### **RAIL-TO-RAIL OUTPUT**

A class AB output stage with common-source transistors is used to achieve rail-to-rail output. This output stage is capable of driving  $600\Omega$  loads connected to any potential

between V+ and ground. For light resistive loads (>  $50k\Omega$ ), the output voltage can typically swing to within 1mV from supply rail. With moderate resistive loads ( $2k\Omega$  to  $50k\Omega$ ), the output can swing to within a few tens of milli-volts from the supply rails while maintaining high open-loop gain. See the typical performance curve "Output Voltage Swing vs Output Current."

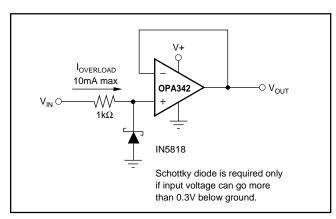


FIGURE 4. Input Current Protection for Voltages Exceeding the Supply Voltage.

#### CAPACITIVE LOAD AND STABILITY

The OPA342 in a unity-gain configuration can directly drive up to 250pF pure capacitive load. Increasing the gain enhances the amplifier's ability to drive greater capacitive loads. See the typical performance curve "Small-Signal"



Overshoot vs Capacitive Load." In unity-gain configurations, capacitive load drive can be improved by inserting a small ( $10\Omega$  to  $20\Omega$ ) resistor,  $R_S$ , in series with the output, as shown in Figure 5. This significantly reduces ringing while maintaining dc performance for purely capacitive loads. However, if there is a resistive load in parallel with the capacitive load, a voltage divider is created, introducing a dc error at the output and slightly reducing the output swing. The error introduced is proportional to the ratio  $R_S/R_L$ , and is generally negligible.

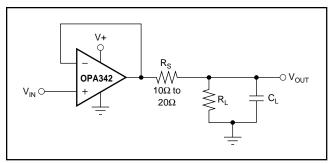


FIGURE 5. Series Resistor in Unity-Gain Configuration Improves Capacitive Load Drive.

#### **DRIVING A/D CONVERTERS**

The OPA342 series op amps are optimized for driving medium-speed sampling ADCs. The OPA342 op amps buffer the ADC's input capacitance and resulting charge injection while providing signal gain.

Figures 6 shows the OPA342 in a basic noninverting configuration driving the ADS7822. The ADS7822 is a 12-bit, micro-power sampling converter in the MSOP-8 package. When used with the low-power, miniature packages of the OPA342, the combination is ideal for space-limited, low-power applications. In this configuration, an RC network at the ADC's input can be used to filter charge injection.

Figure 7 shows the OPA2342 driving an ADS7822 in a speech bandpass filtered data acquisition system. This small, low-cost solution provides the necessary amplification and signal conditioning to interface directly with an electret microphone. This circuit will operate with  $V_S = +2.7V$  to +5V with less than  $500\mu A$  quiescent current.

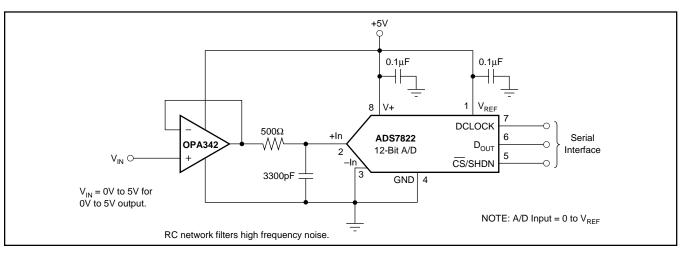


FIGURE 6. OPA342 in Noninverting Configuration Driving ADS7822.

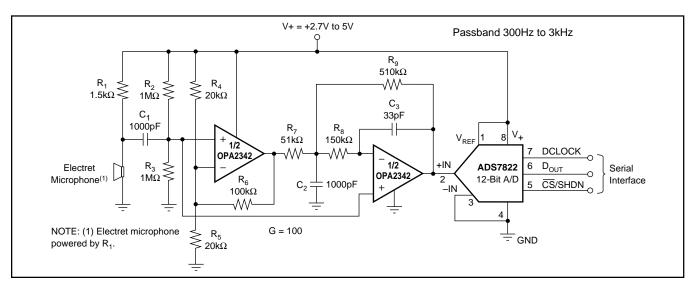


FIGURE 7. Speech Bandpass Filtered Data Acquisition System.







24-Jan-2013

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Sample
OPA2342EA/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR		C42	
OPA2342EA/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR		C42	Sample
OPA2342EA/2K5	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR		C42	Sample
OPA2342EA/2K5G4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR		C42	Sample
OPA2342UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA 2342UA	Sample
OPA2342UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA 2342UA	Sample
OPA2342UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA 2342UA	Sample
OPA2342UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA 2342UA	Sample
OPA342NA/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		B42	Sampl
OPA342NA/250G4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		B42	Sampl
OPA342NA/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		B42	Sampl
OPA342NA/3KG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		B42	Sampl
OPA342UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA 342UA	Sampl
OPA342UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA 342UA	Sampl
OPA4342EA/250	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	OPA 4342EA		Sampl
OPA4342EA/250G4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		OPA 4342EA	Sampl
OPA4342PA	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		OPA4342PA	Sampl



#### PACKAGE OPTION ADDENDUM

24-.lan-2013

Orderable Device	Status	Package Type	_		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C) T	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
OPA4342PAG4	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	OPA	PA4342PA	Samples
OPA4342UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	OPA	PA4342UA	Samples
OPA4342UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	OPA	A4342UA	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used betwee the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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### PACKAGE MATERIALS INFORMATION

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#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All differsions are normal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2342EA/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2342EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2342UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4342EA/250	TSSOP	PW	14	250	180.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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\*All dimensions are nominal

Device	Package Type	Package Type Package Drawing		SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2342EA/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA2342EA/2K5	VSSOP	DGK	8	2500	367.0	367.0	35.0
OPA2342UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0
OPA4342EA/250	TSSOP	PW	14	250	210.0	185.0	35.0

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